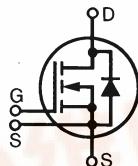




CoolMOS Power MOSFET

N-Channel Enhancement Mode
Low $R_{DS(on)}$, High V_{DSS} MOSFET

IXKN 40N60C



COOLMOS
Power Semiconductors

V_{DSS}	I_{D25}	$R_{DS(on)}$
600 V	40 A	70 mΩ

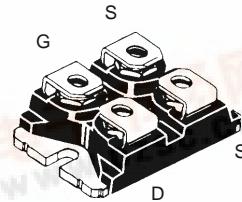
Symbol	Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	600	V	
V_{GS}		± 20	V	
I_{D25}	$T_C = 25^\circ\text{C}$	40	A	
I_{D90}	$T_C = 90^\circ\text{C}$	27	A	
E_{AR}	$I_D = 20 \text{ A}$, $L = 5 \mu\text{H}$, $T_{VJ} = 25^\circ\text{C}$, repetitive	1	mJ	
E_{AS}	$I_D = 10 \text{ A}$, $L = 36 \text{ mH}$, $T_{VJ} = 25^\circ\text{C}$, non repetitive	1.8	J	
dv/dt	$V_{DS} \leq V_{DSS}$, $I_S = 47 \text{ A}$, $di_S/dt = 100 \text{ A}/\mu\text{s}$, $T_J = T_{JM}$	6	V/ns	
P_D	$T_C = 25^\circ\text{C}$	290	W	
T_J		-40 ... +150	°C	
T_{JM}		150	°C	
T_{stg}		-40 ... +150	°C	
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	2500	V~	
M_d	Mounting torque Terminal connection torque (M4)	1.5/13	Nm/lb.in.	
		1.5/13	Nm/lb.in.	

MOSFET

Symbol	Conditions	Characteristic Values			
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.	max.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 1 \text{ mA}$	600			V
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	0.5 50	25 μA	μA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$			70	mΩ
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 2.5 \text{ mA}$	3.5		5.5	V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$			± 100	nA

miniBLOC, SOT-227 B

E72873



G = Gate
S = Source
D = Drain

Either source terminal at miniBLOC can be used as main or kelvin source

Features

- miniBLOC package
 - Electrically isolated copper base
 - Low coupling capacitance to the heatsink for reduced EMI
 - High power dissipation due to AlN ceramic substrate
 - International standard package SOT-227
 - Easy screw assembly
- Fast CoolMOS power MOSFET
 - High blocking capability
 - Low on resistance
 - Avalanche rated for unclamped inductive switching (UIS)
 - Low thermal resistance due to reduced chip thickness
- Enhanced total power density

Applications

- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

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Symbol	Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$	30	S	
C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	8.8	nF	
C_{oss}		3.15	nF	
C_{rss}		36	pF	
$Q_{g(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 350 \text{ V}, I_D = I_{D25}$	220	nC	
Q_{gs}		56	nC	
Q_{gd}		123	nC	
$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 350 \text{ V}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1.8 \Omega$ (External)	28	ns	
t_r		95	ns	
$t_{d(off)}$		100	ns	
t_f		10	ns	
R_{thJC}		0.43	K/W	
R_{thCK}		0.05	K/W	

Source-Drain Diode

Symbol	Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_{SD}	$I_F = 0.5 \cdot I_{D25}, V_{GS} = 0 \text{ V}$	0.9	1.1	V
t_{rr}	$I_F = 47 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}, V_R = 350 \text{ V}, T_J = 25^\circ\text{C}$	650		ns
I_{RM}		110		A

Package

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
Weight		30		g

